

Fein Focus Series FXS 100.23

Real Time X-Ray Imaging System

DESCRIPTION:

- Used for observing semiconductor bonds, bare board registration of inner layers, populated PWB solder joints, ceramic material flaws, etc.
- Non-contact, non-destructive inspection
- Integrated X-Y-Z manipulation system
- Tilt and rotate control
- Real-time video imaging
- Magnification zoom of 2X to 80X
- Maximum sample size 12"x15"
- Voiding calculation & BGA inspection software.



LOCATION: IEEC RELIABILITY LAB

[CONTACT US](#)

CONTACTS

For more information or to arrange for the use of this equipment, contact any of the IEEC staff members listed below:

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